DOSEMI

IGBT

DG50X12T2

1200V/50A IGBT with Diode

General Description

DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as general inverters and UPS.

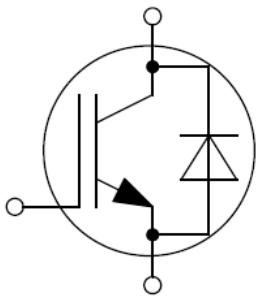
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- Maximum junction temperature 175°C
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD
- Lead free package

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Equivalent Circuit Schematic



Absolute Maximum Ratings T_C=25°C unless otherwise noted

IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	±20	V
I_C	Collector Current @ T_C=25°C @ T_C=134°C	100 50	A
I_{CM}	Pulsed Collector Current t_p=1ms	200	A
P_D	Maximum Power Dissipation @ T_j=175°C	1049	W

Diode

Symbol	Description	Values	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	50	A
I_{FM}	Diode Maximum Forward Current t_p=1ms	200	A

Discrete

Symbol	Description	Values	Unit
T_{jop}	Operating Junction Temperature	-40 to +175	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C
T_S	Soldering Temperature,1.6mm from case for 10s	260	°C

IGBT Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C=50A,V_{GE}=15V, T_j=25°C		1.75	2.20	V
		I_C=50A,V_{GE}=15V, T_j=125°C		2.00		
		I_C=50A,V_{GE}=15V, T_j=150°C		2.05		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C=1.80mA,V_{CE}=V_{GE}, T_j=25°C	5.6	6.2	6.8	V
I_{CES}	Collector Cut-Off Current	V_{CE}=V_{CES},V_{GE}=0V, T_j=25°C			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	V_{GE}=V_{GES},V_{CE}=0V, T_j=25°C			400	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance	V_{CE}=25V,f=1MHz, V_{GE}=0V		4.66		nF
C_{res}	Reverse Transfer Capacitance			0.13		nF
Q_G	Gate Charge	V_{GE}=-15…+15V		0.35		μC
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=50A, R_G=15Ω,V_{GE}=±15V, T_j=25°C		137		ns
t_r	Rise Time			26		ns
$t_{d(off)}$	Turn-Off Delay Time			323		ns
t_f	Fall Time			78		ns
E_{on}	Turn-On Switching Loss			4.88		mJ
E_{off}	Turn-Off Switching Loss			2.74		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=50A, R_G=15Ω,V_{GE}=±15V, T_j=125°C		146		ns
t_r	Rise Time			34		ns
$t_{d(off)}$	Turn-Off Delay Time			421		ns
t_f	Fall Time			147		ns
E_{on}	Turn-On Switching Loss			6.59		mJ
E_{off}	Turn-Off Switching Loss			4.21		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=50A, R_G=15Ω,V_{GE}=±15V, T_j=150°C		146		ns
t_r	Rise Time			34		ns
$t_{d(off)}$	Turn-Off Delay Time			441		ns
t_f	Fall Time			166		ns
E_{on}	Turn-On Switching Loss			7.19		mJ
E_{off}	Turn-Off Switching Loss			4.69		mJ
I_{SC}	SC Data	t_P≤10μs,V_{GE}=15V, T_j=150°C,V_{CC}=900V, V_{CEM}≤1200V		200		A

Diode Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	I_F=50A,V_{GE}=0V,T_j=25°C		1.85	2.30	V
		I_F=50A,V_{GE}=0V,T_j=125°C		1.90		
		I_F=50A,V_{GE}=0V,T_j=150°C		1.95		
Q_r	Recovered Charge	V_R=600V,I_F=50A, -di/dt=1400A/μs,V_{GE}=-15V T_j=25°C		6.3		μC
I_{RM}	Peak Reverse Recovery Current			62		A
E_{rec}	Reverse Recovery Energy			1.67		mJ
Q_r	Recovered Charge	V_R=600V,I_F=50A, -di/dt=1400A/μs,V_{GE}=-15V T_j=125°C		10.1		μC
I_{RM}	Peak Reverse Recovery Current			69		A
E_{rec}	Reverse Recovery Energy			2.94		mJ
Q_r	Recovered Charge	V_R=600V,I_F=50A, -di/dt=1400A/μs,V_{GE}=-15V T_j=150°C		11.5		μC
I_{RM}	Peak Reverse Recovery Current			72		A
E_{rec}	Reverse Recovery Energy			3.63		mJ

Discrete Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			0.143 0.247	K/W
R_{thJA}	Junction-to-Ambient		40		K/W

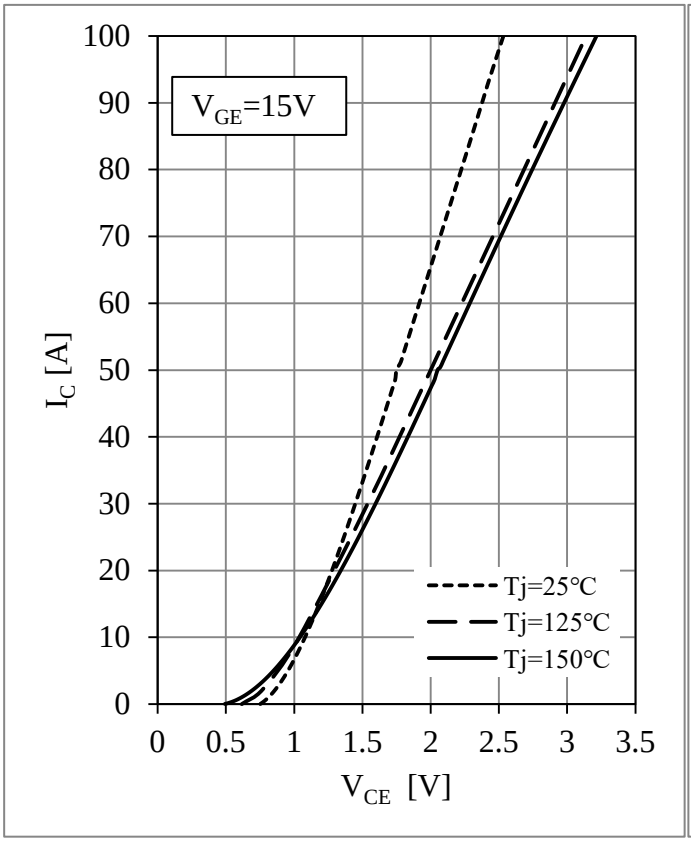


Fig 1. IGBT-inverter Output Characteristics

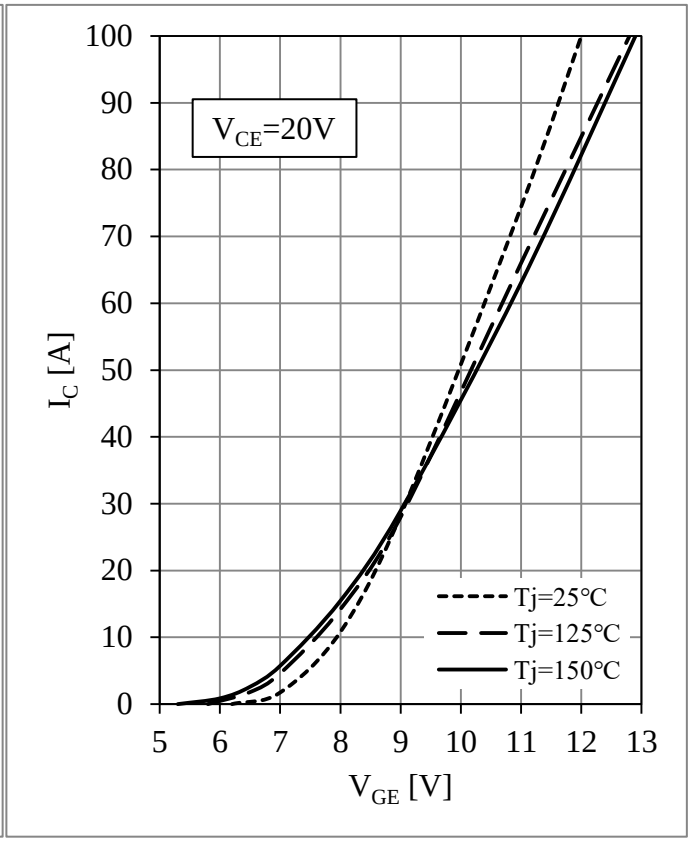


Fig 2. IGBT-inverter Transfer Characteristics

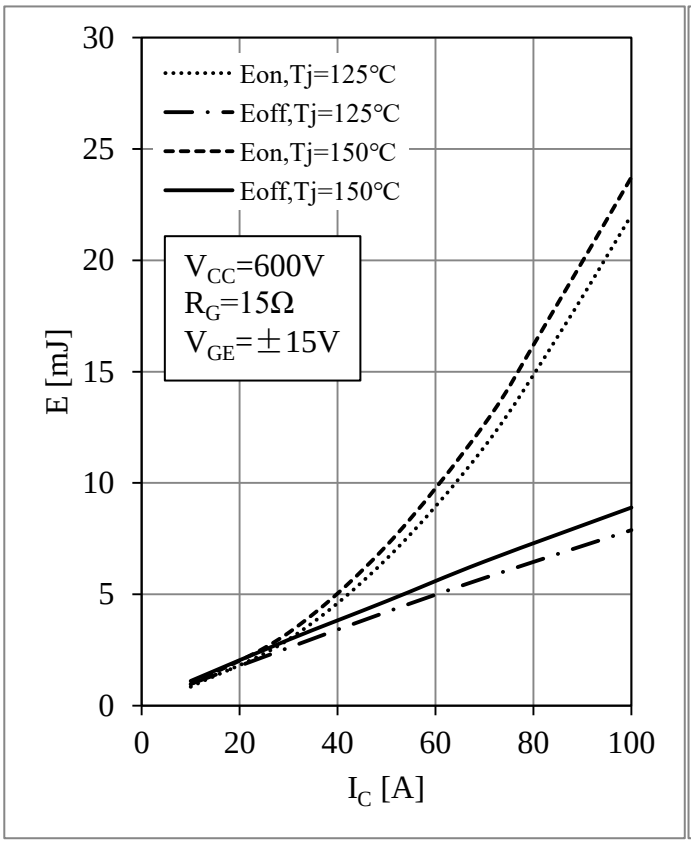


Fig 3. IGBT-inverter Switching Loss vs. I_C

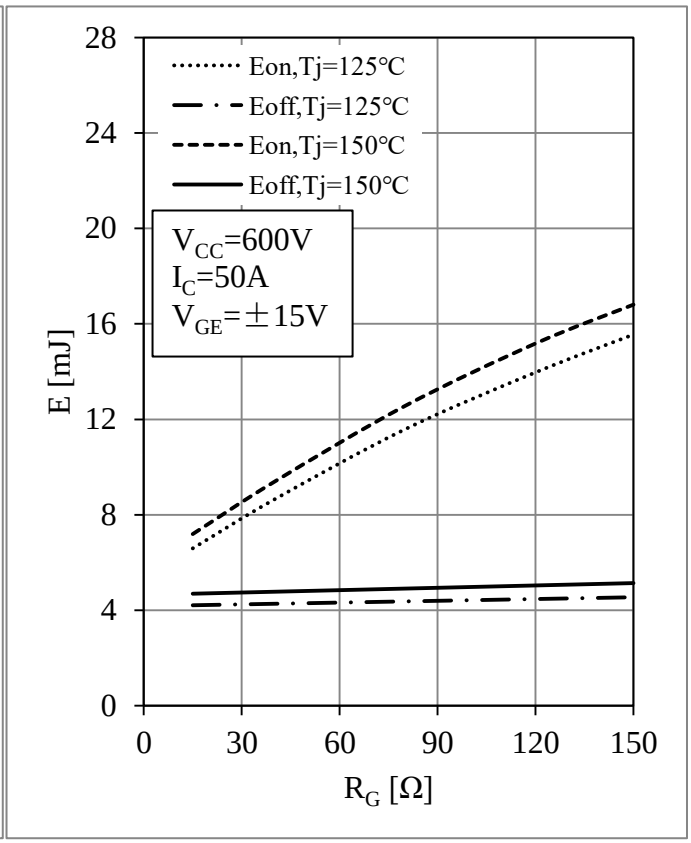


Fig 4. IGBT-inverter Switching Loss vs. R_G

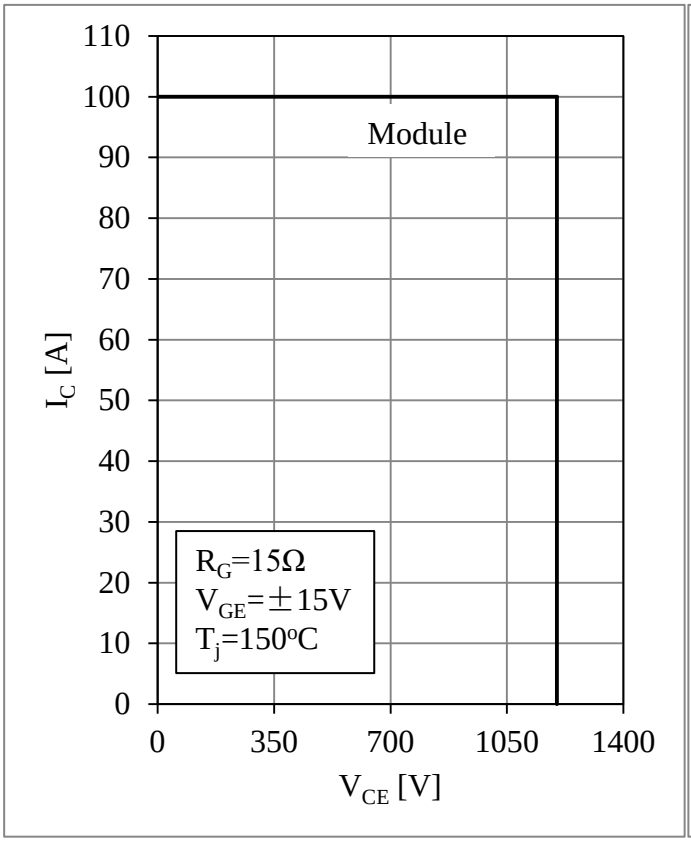


Fig 5. IGBT-inverter RBSOA

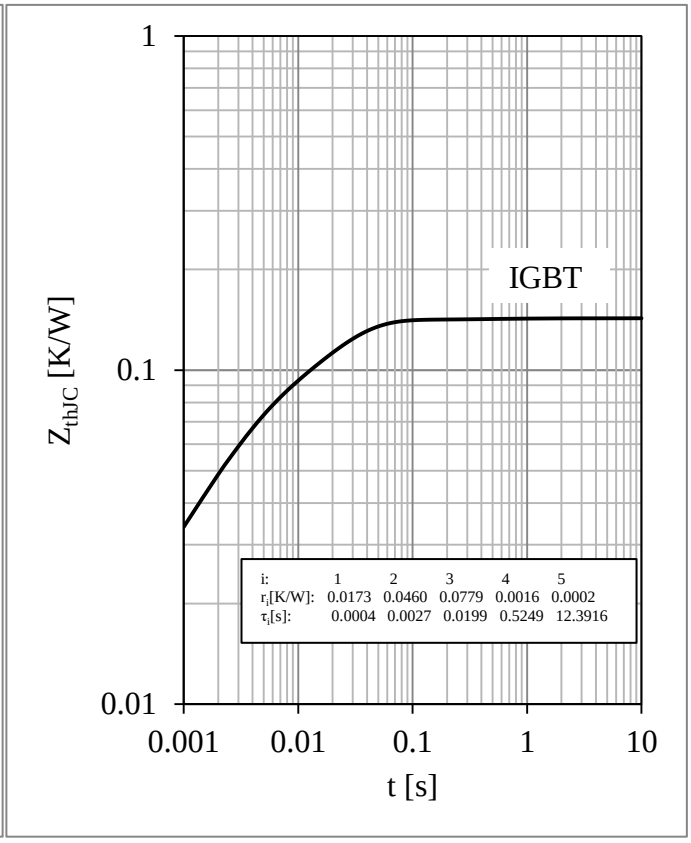


Fig 6. IGBT-inverter Transient Thermal Impedance

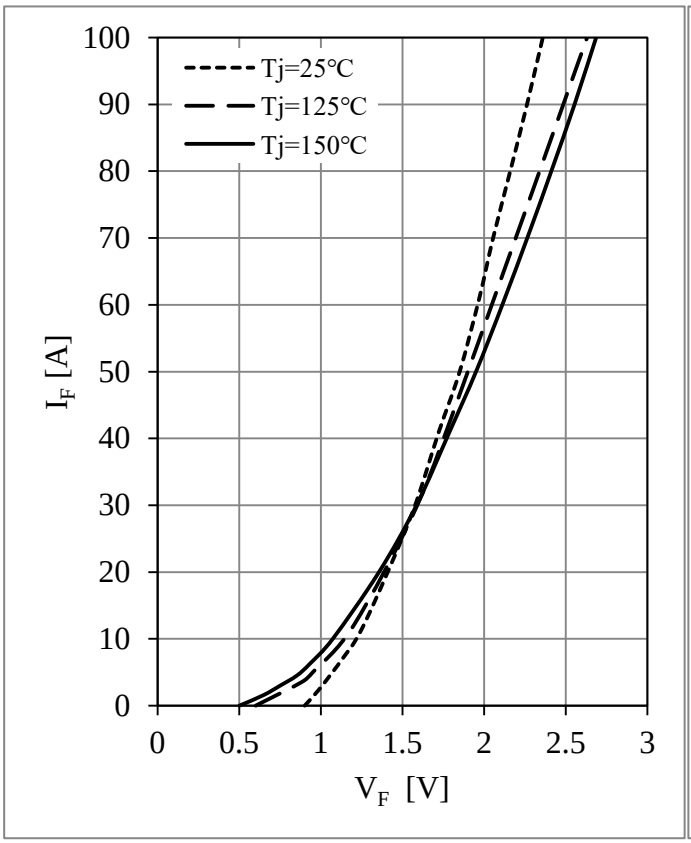


Fig 7. Diode-inverter Forward Characteristics

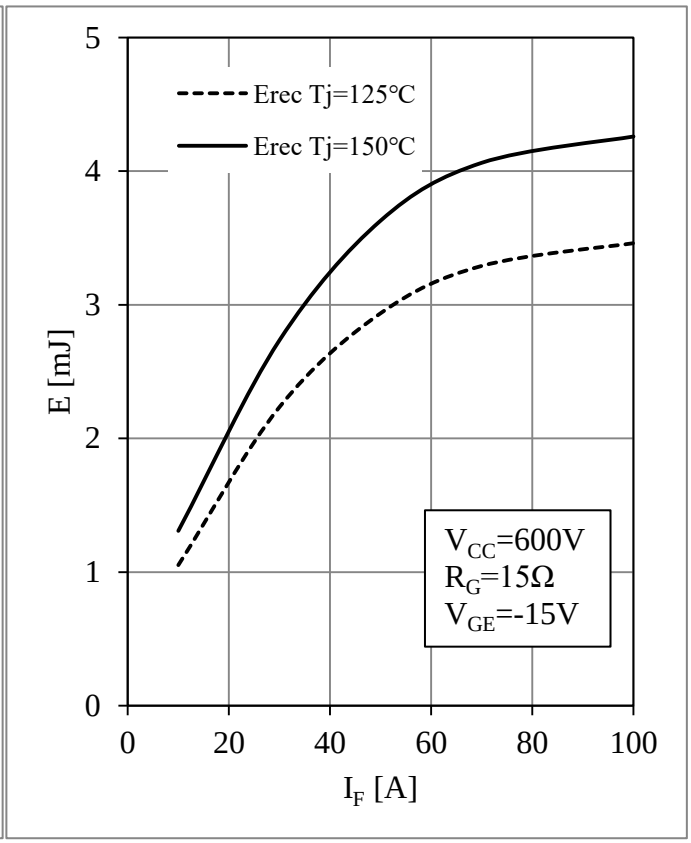


Fig 8. Diode-inverter Switching Loss vs. I_F

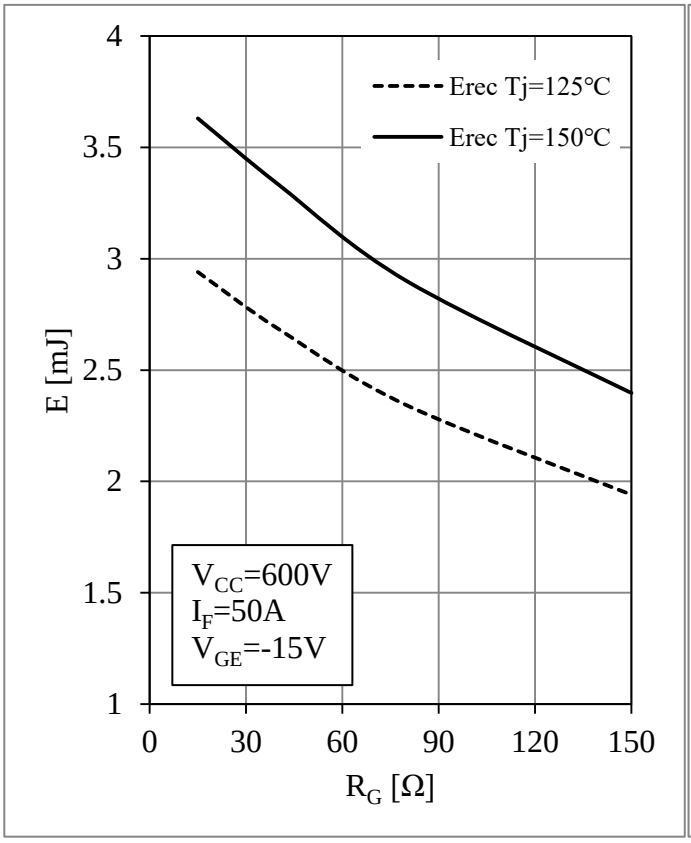


Fig 9. Diode-inverter Switching Loss vs. R_G

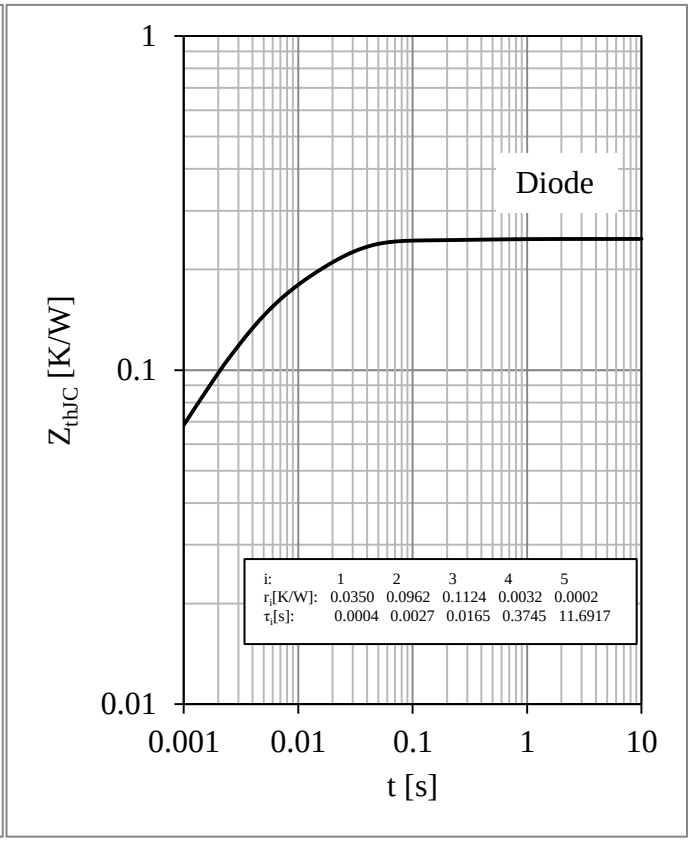
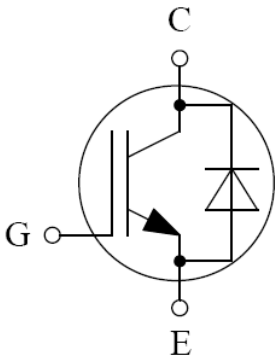


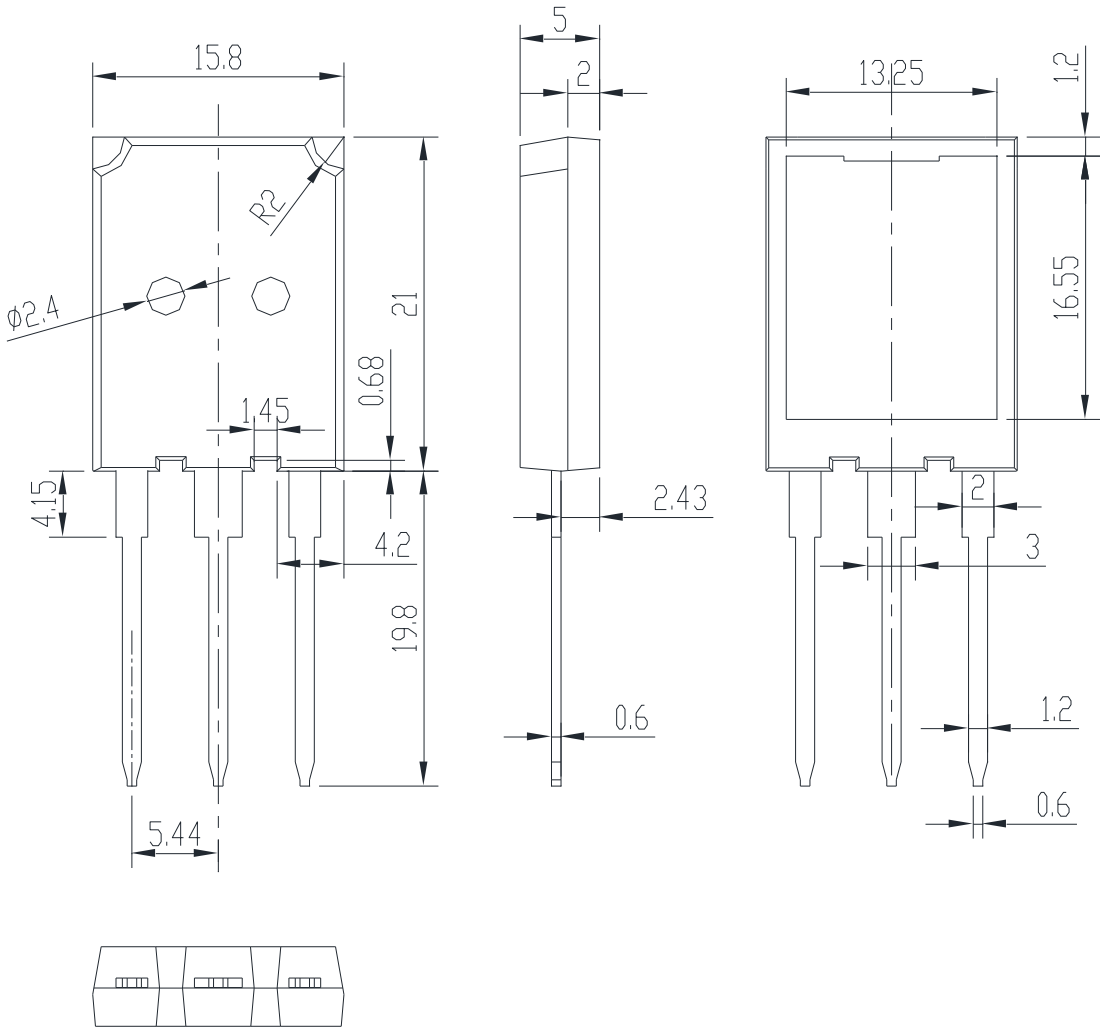
Fig 10. Diode-inverter Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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